IPC ASSOCIATION CONNECTION ELECTRONICS INDUSTRIE	© Copyright 2005. IPC,	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both This docur level parts.	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1					Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information			
upplier Inform	nation													
Company name*			Company unique ID			Unique ID Authority				Respon	Response Date*			
nsemi										2024-05	2024-05-16			
Contact Name			Title - Contact			Phone - Contact*				Email - Contact*				
Product-Env-Stew	ards		Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
uthorized Repres	entative*		Title - Representative			Phone - Representative*			Email -	Email - Representative*				
Product-Env-Stew	ards		Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Request	er Item Number	Mfr Item Number		Mfr Item Name		Effective D	ate V	ersion	Manufacturing Site		Weight*	UOM	Unit Type	
		NCP1616A2DR2G High Voltage Hig Correction Contro		High Voltage High Correction Control	Efficiency Power Factor ler	2024-05-16	5	PH1			76.13	mg	Each	
lanufacturing	Proccess Informatio	n												
Terminal Plating / Grid Array Material Ter			erminal Base Alloy J-STD-020 MSL Rati		STD-020 MSL Rating	Peak Process Body Temperature Max Time at I			ure Max Time at Peal	ak Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed		C	CU Alloy 1			260	C 30		30	secoi	nds 3			
omments														
vel 1 - maximum	time at peak temperature	during solo	dering is 10-3	30 seconds										
or more informat	ion regarding material cor	nposition r	olease refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have not written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Islability and the Company's remedies for issues that arise regarding information the Supplier provide										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.62	mg	Supplier	Silicon (Si)	7440-21-3		2.62	mg
Die Attach Epoxy	0.39	mg		Epoxy resin	proprietary data		0.2535	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.1365	mg
Lead Frame	21.32		Supplier	Silver (Ag)	7440-22-4		0.3624	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0256	mg
			Supplier	Iron (Fe)	7439-89-6		0.501	mg
			Supplier	Copper (Cu)	7440-50-8		20.4246	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0064	mg
Mold Compound-Black	50.28	mg		Epoxy resin	proprietary data		2.514	mg
			Supplier	Phenolic Resin	Proprietary Data		1.0056	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.257	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2514	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		45.252	mg
Plating	1.37	mg	Supplier	Tin (Sn)	7440-31-5		1.37	mg
Wire Bond - Au	0.15	mg	Supplier	Gold (Au)	7440-57-5		0.15	mg